



DT05 PCT/PTO 12 NOV 2002 CT

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Kunihiro SHIMA

ATTN: Application Branch

Application No.: 09/926,758

Attorney Dkt. No.: 108384-00036

Filed: December 13, 2001

For: METHOD OF MODIFYING PROPERTIES OF HIGH-STRENGTH, HIGH-CONDUCTIVITY CU-AG ALLOY PLATE, AND METHOD OF PRODUCING HIGH-STRENGTH, HIGH-CONDUCTIVITY CU-AG ALLOY PLATE

REQUEST FOR CORRECTED FILING RECEIPT

Commissioner for Patents
Washington, D.C. 20231

November 12, 2002

Sir:

A further corrected filing receipt is hereby requested in view of the errors which appear in the first corrected filing receipt. For the convenience of the Patent and Trademark Office, attached is a photocopy of the first corrected filing receipt and Declaration on which the errors have been noted in red.

Please charge any deficiency or credit any overpayment with respect to this paper to Deposit Account No. 01-2300.

Respectfully submitted,

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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/926,758	12/13/2001	1742	890	108384-00036	5	4	2

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CONFIRMATION NO. 3728
CORRECTED FILING RECEIPT



OC000000008905492

Date Mailed: 10/04/2002

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Kunihiro Shima, Kanagawa, JAPAN;

Domestic Priority data as claimed by applicant

This application is a 371 of PCT/JP01/02986 04/06/2001

Foreign Applications

JAPAN 2000-114756 04/17/2000

Projected Publication Date: None, application placed under Secrecy Order.

Non-Publication Request: No

Early Publication Request: No

Title

Modifying Method of *conductivity* modifying properties of high-strength, high-conductivity Cu-AG alloy plate an method of producing high-strength, high conductivity Cu-AG plate

Preliminary Class

Docket No. _____

ARENT FOX KINTNER PLOTKIN & KAHN, PLLC
Nikaido, Marmelstein, Murray & Oram Intellectual Property Group

Declaration For U.S. Patent Application

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

(Insert Title) METHOD OF MODIFYING PROPERTIES OF HIGH-STRENGTH, HIGH-CONDUCTIVITY CU-AG ALLOY PLATE AND

METHOD OF PRODUCING HIGH-STRENGTH, HIGH-CONDUCTIVITY CU-AG ALLOY PLATE

the specification of which is attached hereto unless the following box is checked:

☐ was filed on April 6, 2001 as PCT International Application
Number PCT/JP01/02986 and was amended on _____
and/or was filed on _____ as United States Application
Number _____ and was amended on _____

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claim(s), as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in 37 C.F.R. §1.56.

I hereby claim foreign priority benefits under 35 U.S.C. §119(a)-(d) or §365(b) of any foreign application(s) for patent or inventor's certificate, or §365(a) of any PCT International application which designated at least one country other than the United States, listed below and have also identified below any foreign application for patent or inventor's certificate or PCT International Application having a filing date before that of the application(s) for which priority is claimed:

(List prior foreign applications. See note A on back of this page)	2000-114756	Japan	17 April 2000	Priority Claimed
	(Number)	(Country)	(Day/Month/Year Filed)	<input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
	(Number)	(Country)	(Day/Month/Year Filed)	<input type="checkbox"/> Yes <input type="checkbox"/> No
	(Number)	(Country)	(Day/Month/Year Filed)	<input type="checkbox"/> Yes <input type="checkbox"/> No

I hereby claim the benefit under 35 U.S.C. §119(e) of any United States provisional application(s) listed below.

(Application Number)	(Filing Date)
(Application Number)	(Filing Date)

(See Note B on back of this page)

☐ See attached list for additional prior foreign or provisional applications.

I hereby claim the benefit under 35 U.S.C. §120 of any United States application(s) or §365(c) of any PCT International application(s) designating the United States of America listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior application(s) (U.S. or PCT) in the manner provided by the first paragraph of 35, U.S.C. §112, I acknowledge the duty to disclose information which is material to patentability as defined in 37 C.F.R. §1.56 which became available between the filing date of the prior application and the national or PCT International filing date of this application.

(List prior U.S. Applications or PCT International applications designating the U.S.)	(Application Serial No.)	(Filing Date)	(Status) (patented, pending, abandoned)
	(Application Serial No.)	(Filing Date)	(Status) (patented, pending, abandoned)

And I hereby appoint as principal attorneys: David T. Nikaido, Reg. No. 22,663; Charles M. Marmelstein, Reg. No. 25,895; George E. Oram, Jr., Reg. No. 27,931; Robert B. Murray, Reg. No. 22,980; E. Marcie Emas, Reg. No. 32,131; Douglas H. Goldhush, Reg. No. 33,125; Monica Chin Kitts, Reg. No. 36,105; Richard J. Berman, Reg. No. 39,107; King L. Wong, Reg. No. 37,500; James A. Poulos, III, Reg. No. 31,714; Patrick D. Muir, Reg. No. 37,403; Sharon N. Klesner, Reg. No. 36,335; Murat Ozgu, Reg. No. 44,275; Bradley D. Goldizen, Reg. No. 43,637, and N. Alexander Nolte, Reg. No. 45,689.

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further, that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

(See Note C on back of this page)

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25/9/2001
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